SDAS036D - APRIL 1982 - REVISED AUGUST 1995

- 3-State Buffer-Type Outputs Drive Bus Lines Directly
- Bus-Structured Pinout
- Package Options Include Plastic Small-Outline (DW) Packages, Ceramic Chip Carriers (FK), and Plastic (NT) and Ceramic (JT) DIPs

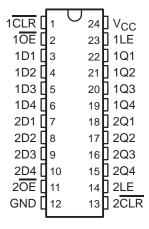
description

These dual 4-bit D-type latches feature 3-state outputs designed specifically for bus driving. These devices are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

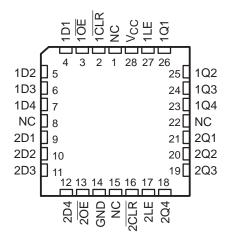
The dual 4-bit latches are transparent D-type latches. While the latch-enable (LE) input is high, the Q outputs follow the data (D) inputs in true form, according to the function table. When LE is low, the outputs are latched. When the clear ($\overline{\text{CLR}}$) input goes low, the Q outputs go low independently of LE. The outputs are in the high-impedance state when the output-enable ($\overline{\text{OE}}$) input is at a high logic level.

The SN54ALS873B and SN54AS873A are characterized for operation over the full military temperature range of -55°C to 125°C. The SN74ALS873B and SN74AS873A are characterized for operation from 0°C to 70°C.

SN54ALS873B, SN54AS873A . . . JT PACKAGE SN74ALS873B, SN74AS873A . . . DW OR NT PACKAGE (TOP VIEW)



SN54ALS873B, SN54AS873A . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

FUNCTION TABLE (each latch)

	INPU		OUTPUT	
ŌE	CLR	LE	D	Q
L	L	Х	Х	L
L	Н	Н	Н	Н
L	Н	Н	L	L
L	Н	L	X	Q_0
Н	X	Χ	Χ	Z

SN54ALS873B, SN54AS873A, SN74ALS873B, SN74AS873A **DUAL 4-BIT D-TYPE LATCHES**

WITH 3-STATE OUTPUTS

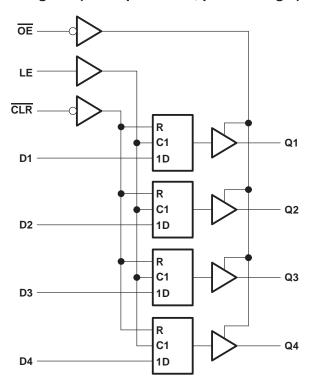
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logic symbol[†]

2 ΕN 10E 23 1LE C1 1 1CLR С 3 22 1D1 1D \triangleright ∇ 1Q1 4 21 1D2 1Q2 5 20 1D3 1Q3 6 19 1D4 1Q4 2OE ΕN 14 2LE C1 13 2CLR С 18 1D 2D1 ∇ 2Q1 \triangleright 8 17 2D2 2Q2 9 16 2Q3 2D3 15 10 2D4 2Q4

Pin numbers shown are for the DW, JT, and NT packages.

logic diagram (each quad latch, positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage, V _{CC}	7 V
Input voltage, V _I	
Voltage applied to a disabled 3-state output	
Operating free-air temperature range, T _A : SN54ALS873B	-55°C to 125°C
SN74ALS873B	0°C to 70°C
Storage temperature range	-65°C to 150°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		SN54ALS873B			SN74ALS873B			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.7			0.8	V
lOH	High-level output current			-1			-2.6	mA
loL	Low-level output current			12			24	mA
TA	Operating free-air temperature	-55		125	0		70	°C



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CO	TEST CONDITIONS		4ALS87	'3B	SN7	4ALS87	3B	UNIT	
PARAMETER	IESI CC	MUITIONS	MIN	TYP [†]	MAX	MIN	TYP [†]	MAX	UNIT	
VIK	V _{CC} = 4.5 V,	$I_{I} = -18 \text{ mA}$			-1.2			-1.2	V	
	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -0.4 \text{ mA}$	V _{CC} -2	}		V _{CC} -2				
Voн	V _{CC} = 4.5 V	$I_{OH} = -1 \text{ mA}$	2.4	3.3					V	
		$I_{OH} = -2.6 \text{ mA}$				2.4	3.2			
Vo	V _{CC} = 4.5 V	I _{OL} = 12 mA		0.25	0.4		0.25	0.4	V	
VOL		I _{OL} = 24 mA					0.35	0.5	V	
lozh	V _{CC} = 5.5 V,	V _O = 2.7 V			20			20	μΑ	
lozL	V _{CC} = 5.5 V,	$V_0 = 0.4 V$			-20			-20	μΑ	
l _l	$V_{CC} = 5.5 \text{ V},$	V _I = 7 V			0.1			0.1	mA	
lіН	$V_{CC} = 5.5 \text{ V},$	V _I = 2.7 V			20			20	μΑ	
I _{IL}	$V_{CC} = 5.5 V,$	V _I = 0.4 V			- 0.2			- 0.2	mA	
1 ₀ ‡	V _{CC} = 5.5 V,	V _O = 2.25 V	-20		-112	-30		-112	mA	
		Outputs high		11	21		11	21	mA	
^I cc	V _{CC} = 5.5 V	Outputs low		16	29		16	29		
		Outputs disabled		20	31		20	31		

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

		!			SN74AL	UNIT		
			MIN	MAX	MIN	MAX		
	Pulse duration	CLR low	15		15		ns	
t _W	Fulse duration	LE high	10		10		115	
t _{su}	t _{SU} Setup time, data before LE↓				10		ns	
th	t _h Hold time, data after LE↓				7		ns	



[‡] The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS.

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switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	C _L : R1 : R2 :	C = 4.5 V = 50 pF, = 500 Ω, = 500 Ω, = MIN to			UNIT
			SN54AL	S873B	SN74AL	S873B	
			MIN	MAX	MIN	MAX	
t _{PLH}	D	Q	2	23	2	14	ns
^t PHL	Б	ų ,	2	17	2	14	113
^t PLH	LE	Q	8	31	8	22	ns
^t PHL		ų ,	8	26	8	21	115
^t PHL	CLR	Q	6	27	6	20	ns
^t PZH	ŌĒ	Q	4	24	4	18	no
^t PZL	OE .	Q Q	4	23	4	18	ns
^t PHZ	ŌĒ	Q	2	12	2	10	no
^t PLZ	OE	Q Q	2	30	2	15	ns

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage, V _{CC}	7 V
Input voltage, V _I	7 V
Voltage applied to a disabled 3-state output	
Operating free-air temperature range, T _A : SN54AS873A	–55°C to 125°C
SN74AS873A	0°C to 70°C
Storage temperature range	–65°C to 150°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		SN54AS873A			SN	UNIT		
		MIN	NOM	MAX	MIN	NOM	MAX	UNII
Vcc	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
V _{IL}	Low-level input voltage			0.8			0.8	V
IOH	High-level output current			-12			-15	mA
l _{OL}	Low-level output current			32			48	mA
TA	Operating free-air temperature	-55		125	0		70	°C

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		SN	54AS87	3A	SN	74AS87	3A	UNIT
PARAMETER	TEST CO	CNDITIONS	MIN	TYP	MAX	MIN	TYP	MAX	UNII
VIK	$V_{CC} = 4.5 \text{ V},$	I _I = -18 mA			-1.2			-1.2	V
	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -2 \text{ mA}$	V _{CC} -2	2		V _{CC} -2	2		
Voн	V _{CC} = 4.5 V	$I_{OH} = -12 \text{ mA}$	2.4	3.2					V
	vCC = 4.5 v	$I_{OH} = -15 \text{ mA}$				2.4	3.3		
V/~·	V 45V	I _{OL} = 32 mA		0.25	0.5				V
VOL	V _{CC} = 4.5 V	I _{OL} = 48 mA					0.35	0.5	V
IOZH	V _{CC} = 5.5 V,	V _O = 2.7 V			50			50	μА
lozL	V _{CC} = 5.5 V,	V _O = 0.4 V			-50			-50	μΑ
ΙĮ	$V_{CC} = 5.5 V,$	V _I = 7 V			0.1			0.1	mA
l _{IH}	$V_{CC} = 5.5 \text{ V},$	V _I = 2.7 V			20			20	μΑ
I _{IL}	$V_{CC} = 5.5 \text{ V},$	V _I = 0.4 V			- 0.5			- 0.5	mA
I _O ‡	V _{CC} = 5.5 V,	V _O = 2.25 V	-30		-112	-30		-112	mA
	I _{CC} V _{CC} = 5.5 V	Outputs high		68	110		68	110	
ICC		Outputs low		67	109		67	109	mA
		Outputs disabled		80	129		80	129	

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

					SN74A	UNIT	
			MIN	MAX	MIN	MAX	ONIT
+ *	Pulse duration	CLR low	5		5		ns
t _W *	ruise duration	LE high	6		5		
t _{su} *	t _{Su} * Setup time, data before LE↓				2		ns
t _h * Hold time, data after LE↓				·	4.5		ns

^{*} On products compliant to MIL-STD-883, Class B, this parameter is based on characterization data but is not production tested.

[‡] The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS.

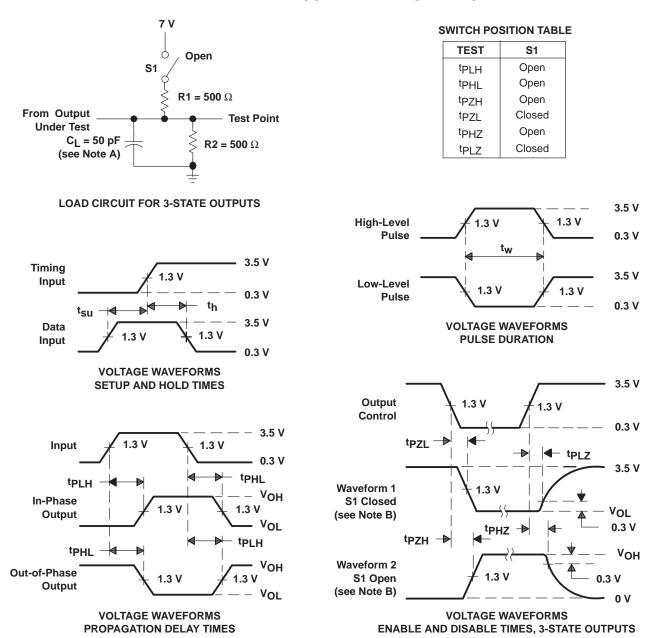
SN54ALS873B, SN54AS873A, SN74ALS873B, SN74AS873A DUAL 4-BIT D-TYPE LATCHES WITH 3-STATE OUTPUTS SDAS036D - APRIL 1982 - REVISED AUGUST 1995

switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _C C _L R1 R2 T _A	UNIT			
			SN54A	S873A	SN74A	S873A	
			MIN	MAX	MIN	MAX	
t _{PLH}	D	Q	3	12.5	3	9.5	ns
t _{PHL}	D		3	8.5	3	7.5	
t _{PLH}	LE	Q	6	15.5	6	13	ns
^t PHL		ά	4	9	4	7.5	115
^t PHL	CLR	Q	3	10.5	3	9	ns
^t PZH	ŌĒ	Q	2	8	2	6.5	ns
t _{PZL}	OE	3	4	11	4	10.5	115
^t PHZ	ŌĒ	Q	2	8	2	7.5	ns
t _{PLZ})L	3	2	8.5	2	7.5	115

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \Omega$, $t_f \leq 2 \text{ ns}$, $t_f \leq 2 \text{ ns}$.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms







PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
84032013A	ACTIVE	LCCC	FK	28	1	TBD	POST-PLATE	N / A for Pkg Type
8403201KA	OBSOLETE	CFP	W	24		TBD	Call TI	Call TI
8403201LA	ACTIVE	CDIP	JT	24	1	TBD	A42 SNPB	N / A for Pkg Type
SN54ALS873BJT	ACTIVE	CDIP	JT	24	1	TBD	A42 SNPB	N / A for Pkg Type
SN74ALS873BDW	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS873BDWE4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS873BDWG4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS873BDWR	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS873BDWRE4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS873BDWRG4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS873BNT	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74ALS873BNT3	OBSOLETE	PDIP	NT	24		TBD	Call TI	Call TI
SN74ALS873BNTE4	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74AS873ADW	OBSOLETE	SOIC	DW	24		TBD	Call TI	Call TI
SN74AS873ADWR	OBSOLETE	SOIC	DW	24		TBD	Call TI	Call TI
SN74AS873ANT	OBSOLETE	PDIP	NT	24		TBD	Call TI	Call TI
SNJ54ALS873BFK	ACTIVE	LCCC	FK	28	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54ALS873BJT	ACTIVE	CDIP	JT	24	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54AS873AFK	OBSOLETE	LCCC	FK	28		TBD	Call TI	Call TI
SNJ54AS873AJT	OBSOLETE	CDIP	JT	24		TBD	Call TI	Call TI
SNJ54AS873AW	OBSOLETE	CFP	W	24		TBD	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.



PACKAGE OPTION ADDENDUM

18-Sep-2008

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION





Α0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

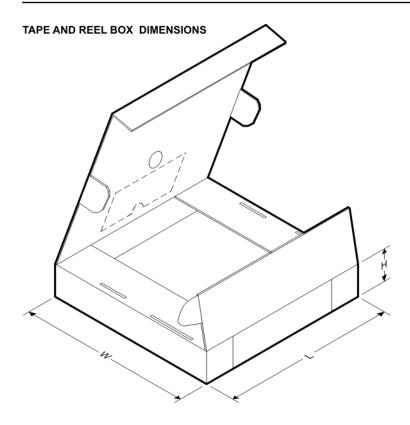
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS873BDWR	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1





*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS873BDWR	SOIC	DW	24	2000	346.0	346.0	41.0

FK (S-CQCC-N**)

28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER



NOTES: A. All linear dimensions are in inches (millimeters).

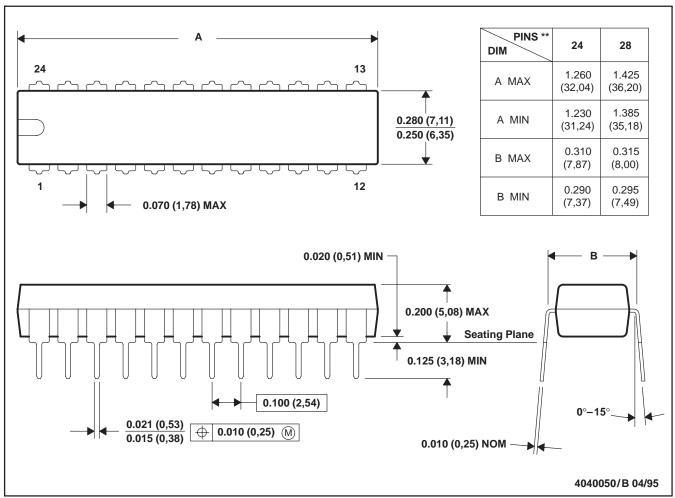
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



NT (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

24 PINS SHOWN

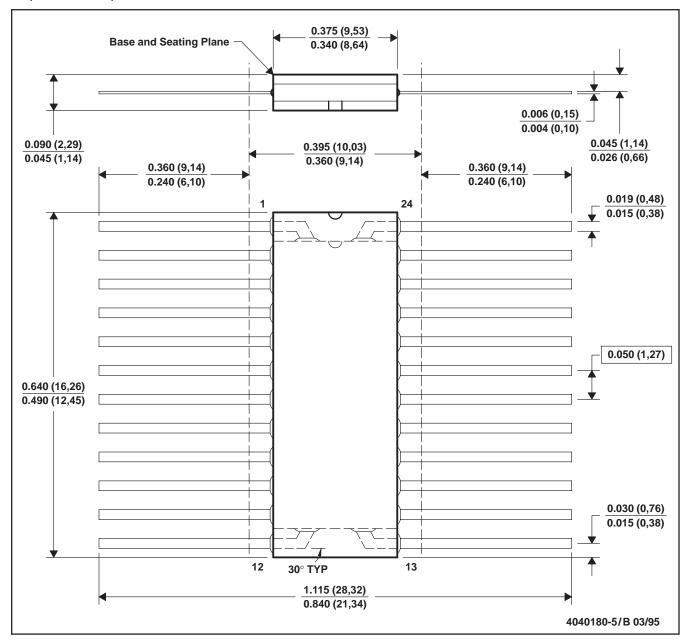


NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

W (R-GDFP-F24)

CERAMIC DUAL FLATPACK



- NOTES: A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Falls within MIL-STD-1835 GDFP2-F24 and JEDEC MO-070AD
 - E. Index point is provided on cap for terminal identification only.



DW (R-PDSO-G24)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AD.



JT (R-GDIP-T**)

24 LEADS SHOWN

CERAMIC DUAL-IN-LINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification.
- E. Falls within MIL STD 1835 GDIP3-T24, GDIP4-T28, and JEDEC MO-058 AA, MO-058 AB

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